

September 10, 2026

Nidec Advance Technology to Exhibit Products at SEMICON INDIA 2026

Nidec Advance Technology Corporation (“Nidec Advance Technology” or the “Company”) announced today that it will exhibit products and solutions at SEMICON INDIA 2026, the flagship event for India’s rapidly expanding semiconductor ecosystem scheduled to be held at Yashobhoomi (India International Convention & Expo Centre), New Delhi, from Thursday, September 17 – Saturday, September 19, 2026.



India’s most influential semiconductor-related event, SEMICON INDIA will be held this year under the theme **“Transform Tomorrow: Silicon to Systems: Building the Ecosystem,”** by inviting more than 500 companies from 20 countries. At this event, Nidec Advance Technology will display the cutting-edge solutions of its probe cards (wafer inspection jigs), while integrating its topnotch optical and electricity inspection and probing technologies to offer inspection solutions that cover the entire semiconductor package-related processes, including wafer, chip, substrate, and package. In addition, the Company will exhibit its products from the TDAS Series (motor/E-Axle test benches) for the auto industry, which is experiencing rapid electrification. These test benches help improve the efficiency of performance evaluation and durability tests, both critical in the development of next-generation EVs.

Further, the Company will introduce E-Transport Simulator®, software to simulate EV vehicle designs and analyses. This program helps reduce the Company’s customers to shorten their test time and reduce costs and strongly supports product development.

About SEMICON INDIA 2026

- Period: Thursday, September 17 – Saturday, September 19, 2026
- Venue: Yashobhoomi (India International Convention & Expo Centre), New Delhi, India
- Booth: H4305, Hall 2

Nidec Advance Technology’s exhibit will include:

- STAR REC Series (server, telecommunications, automotive product, PC, and smartphone substrate inspection equipment)
- GATS Series (automatic semiconductor package inspection equipment)
- NATS Series (power semiconductor inspection equipment)

- RWi-300MK3 (2D/3D wafer bump inspection equipment)
- AURCA Series (3D/AFVI AI inspection system)
- RSH series (optical 2D/3D inspection equipment for high-density substrates)
- High-precision inspection jigs
- TDAS Series (motor/E-Axle test benches)
- E-Transport Simulator® (xEV modeling simulator)
- Semiconductor wafer inspection probe cards

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